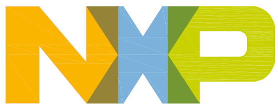

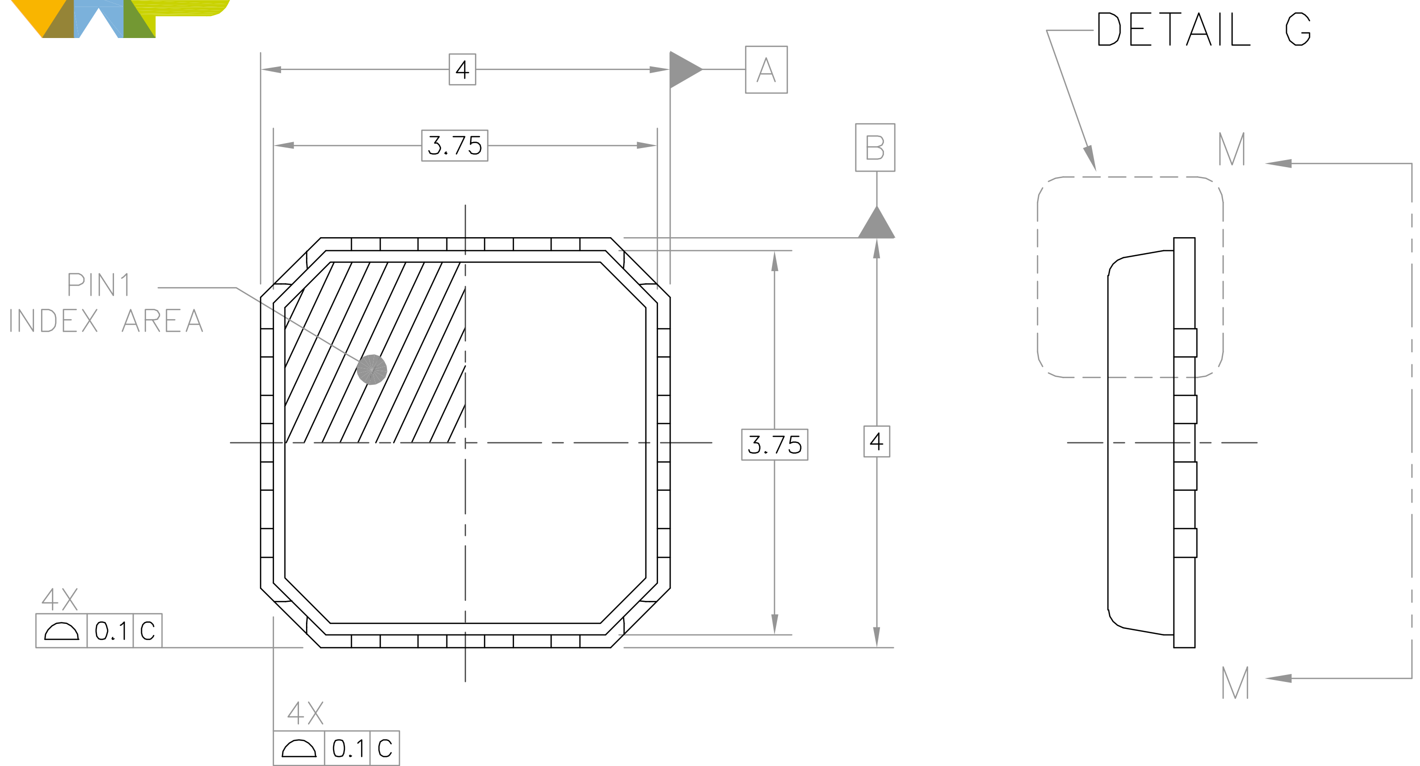

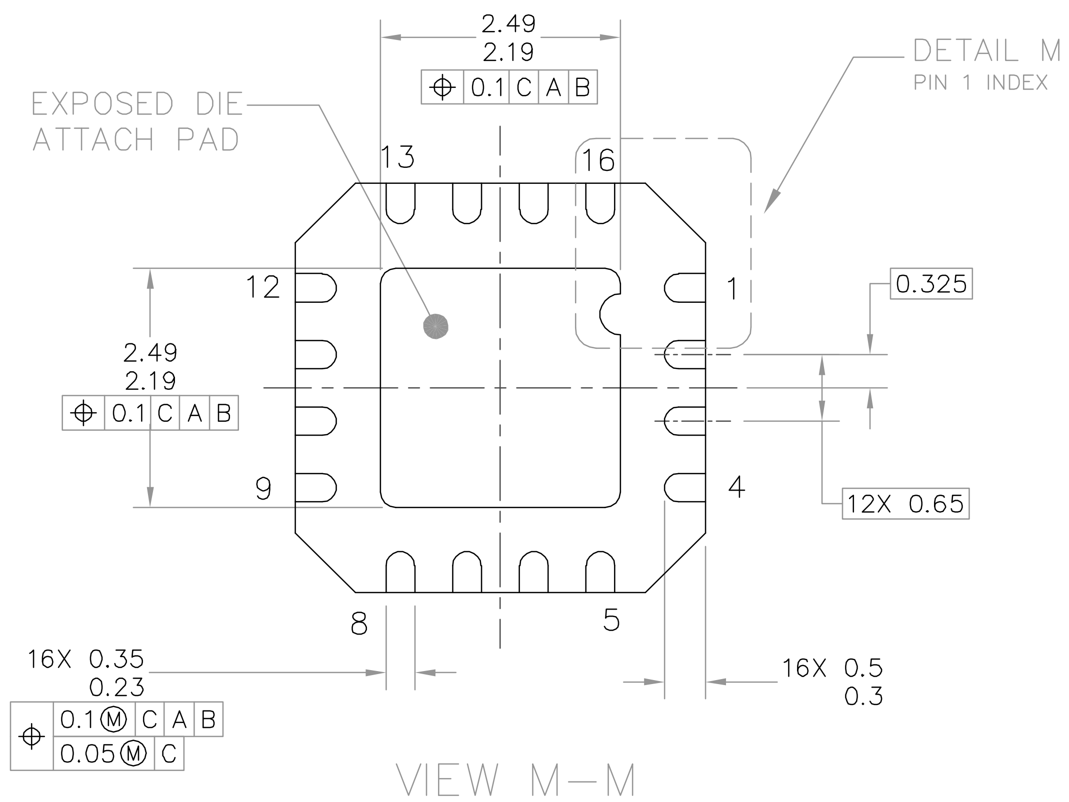

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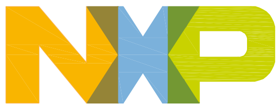
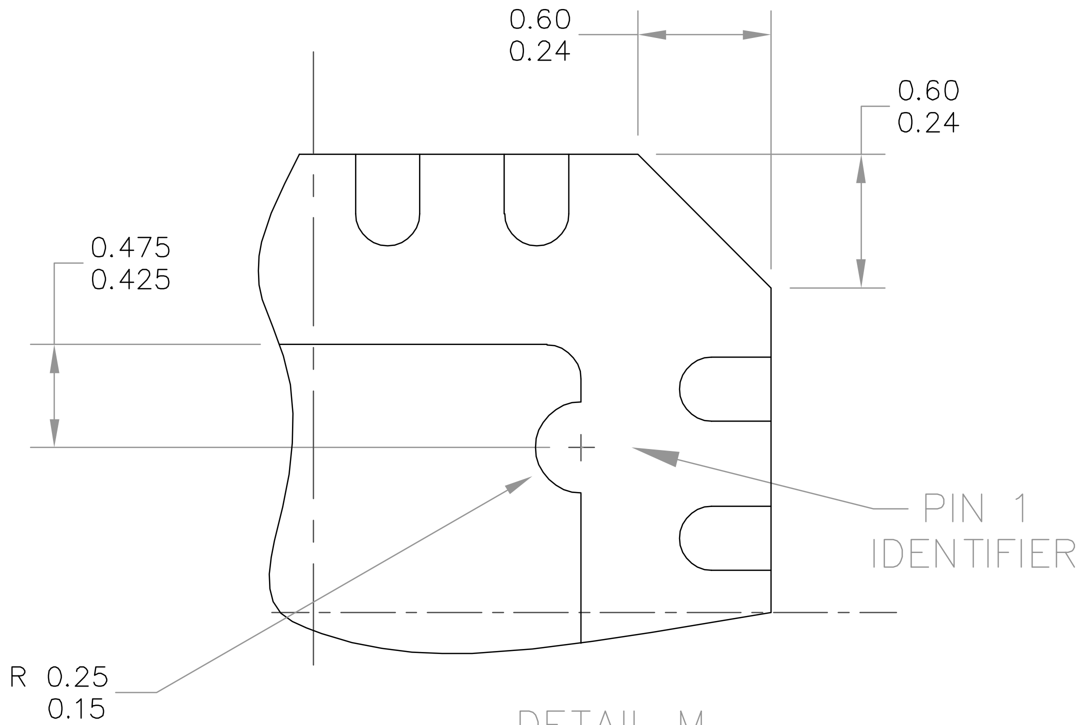
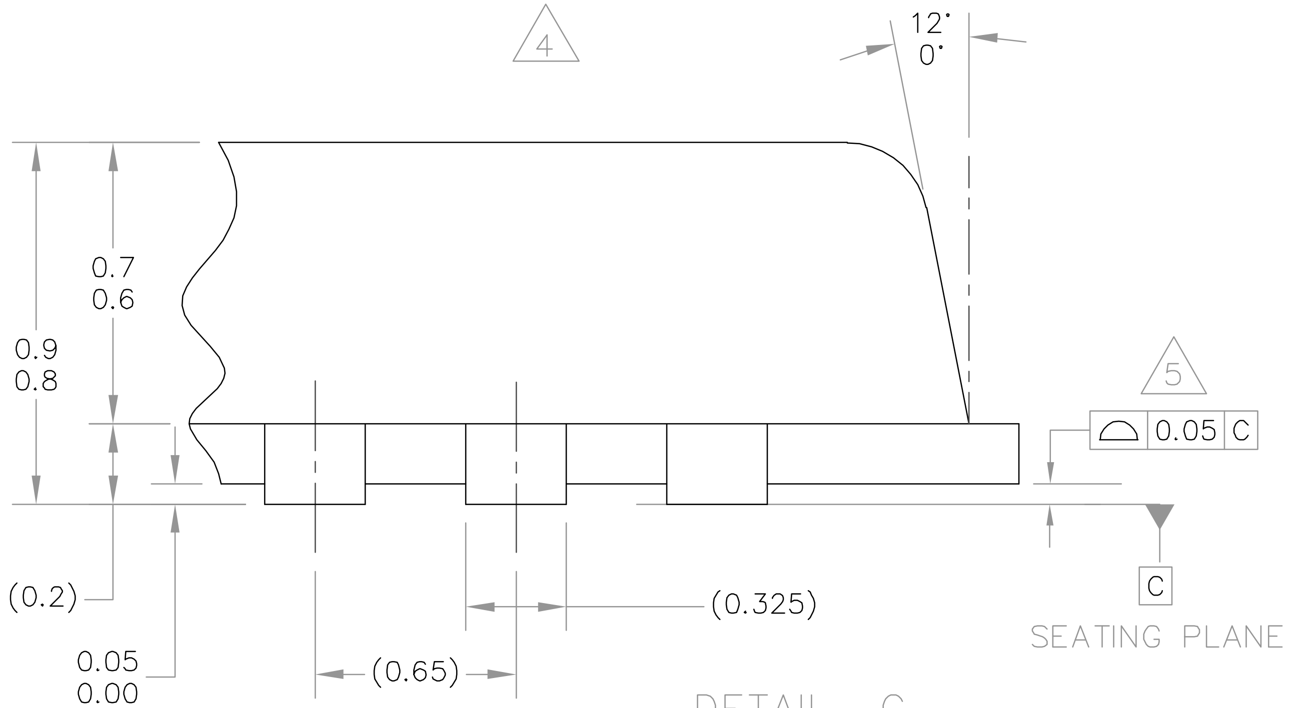
TITLE: THERMALLY ENHANCED QUAD FLAT NON–LEADED PACKAGE (QFN) 16 TERMINAL, 0.65 PITCH (4 X 4 X 0.9)	DOCUMENT NO: 98ASA10761D REV: C
	STANDARD: NON–JEDEC
	SOT1592–1 14 MAR 2016





DETAIL M
PIN 1 BACKSIDE IDENTIFIER



DETAIL G
VIEW ROTATED 90° CW

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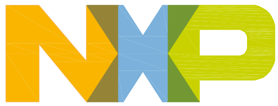
	SOT1592–1 14 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF–PQFN.
4. (△) DIMENSIONS OF OPTIONAL FEATURES ARE FOR REFERENCE ONLY.
5. (△) COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
6. MIN METAL GAP SHOULD BE 0.25MM.

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	SOT1592–1	14 MAR 2016